



(19)

(11) Publication number: 2000058496

Generated Document.

PATENT ABSTRACTS OF JAPAN

(21) Application number: 10226058

(51) Intl. Cl.: H01L 21/304 B08B 3/08

(22) Application date: 10.08.98

(30) Priority:

(43) Date of application
publication: 25.02.00(84) Designated contracting
states:

(71) Applicant: OKI ELECTRIC IND CO LTD

(72) Inventor: OSAKO TAKASHI

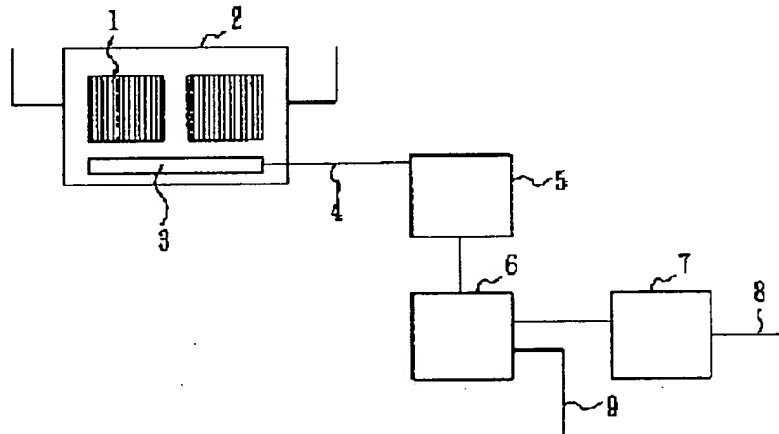
(74) Representative:

(54) OZONE WATER
CLEANING SYSTEM OF
SEMICONDUCTOR WAFER

(57) Abstract:

PROBLEM TO BE SOLVED: To lessen a time required for removing resist from a semiconductor wafer by a method wherein a heater used for heating ozone water is provided onto an ozone water feed line between a cleaning tank and an ozone water generating device.

SOLUTION: An ozone water feed line 4 is connected to an ozone water generating device 6, and a heater 5 is provided to an ozone water feed line 4. A cleaning tank 2 is provided to the outlet of the ozone water feed line 4. In this constitution, ozone water generated by the ozone water generating device 6 is heated by the heater 5 and fed to the cleaning tank 2. Ozone water fed to the cleaning tank 2 is supersaturated as it is kept at high temperatures, and the ozone water gets quickly decomposed because it is kept under a normal pressure when it is introduced into the cleaning tank 2. When a semiconductor wafer 1 is introduced into the cleaning tank 2 that is kept in the condition as mentioned above, ozone reacts quickly on resist. Therefore, a time required for removing resist from a semiconductor wafer can be shortened.



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